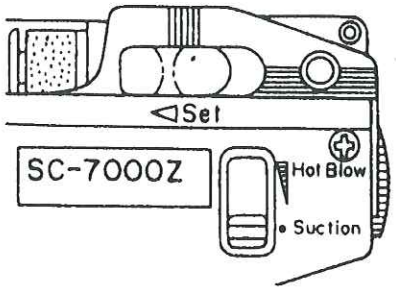
SC-7000Z applicable for removal of SMD with DIC's SMD kit !

◎ APPLICATION AS HOT BLOWER TOOL

1. Remove the desoldering tip by turning it counterclockwise with a wrench (10mm opening) or pliers
2. Fit the SMD hot blow nozzle in place of the desoldering tip.
   Do not tighten too much
3. Remove the filter pipe and the filter cartridge. Then fit the dedicated filter pipe.
4. Set the selector lever to "HOT BLOW" (as Fig.1).
5. Adjust the hot air temperature with the TEMP Knob to accommodate for the removing SMD

CAUTION: To avoid burns, the workings above must be done only when it is cool.



DIC's SMD kit (OPTION)

Filter Pipe

Stainless Steel Wire S-1 × 10PCS

Holder WH-1

Stainless Steel Blade B-1 × 3PCS

SMD Hot Blow nozzle

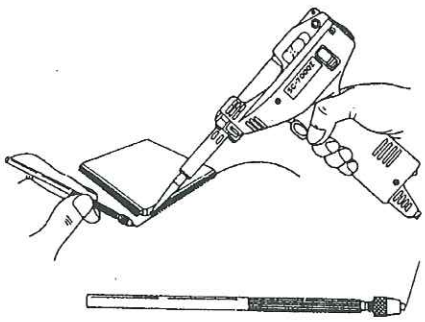


Fig.2

◎ REPAIR OF SMD

1. With a Stainless Steel Wire(S-1) and the Holder(WH-1) for removal of QFP or SOP.

1. Clip a short cut stainless steel wire to the holder. Insert the end of the wire under the SMD legs (as Fig.2).
2. Blow hot air against the legs closest to the wire holder.
   At the solder melting, carefully move the wire forward.
   NOTE: To avoid resoldering, do not blow hot air to the leads already desoldered. Blow it in one direction only. This method can be also applied for removal of a SMD which is densely placed on the PCB. A bent wire can be easily straightened with a long-nose plier and it is usable again.

Fig.3

2. With a Stainless Steel Blade(B-1) and the Holder for removal of PLCC

1. It is most recommendable for PLCC whose IC lead is bent inside.
2. Clip a stainless steel Blade to the holder by loosening the screw on the tip of the holder. Insert the Blade into the holder by approx. 10mm and fasten the screw.
3. The Blade can be cut to a size properly with scissers to make it more manageable (as Fig.3).
4. Keep blowing hot air to the Blade and the legs (as Fig.4). Insert the Blade into an edge of the legs and lightly move the Blade back and forth.
5. For removal of a glued SMD, blow hot air on to the surface of SMD for longer time. Then insert the Blade into the space between the SMD and the PCB to separate the glue.

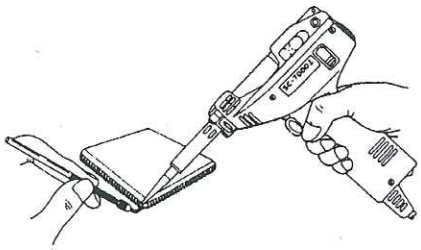


Fig.4

3. For Removal of Chips, Resistors, Capacitors and etc.

1. Suck the solder before hand when it is placed so much.
2. Hold the chip with tweezers and blow hot air to the solder.
   Then remove the chip at the solder melting (as Fig.5).
3. For removal of a glued chip, blow hot air on the surface of chip for longer time. It will be removed without damaging the PCB.

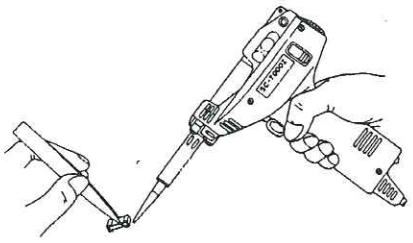


Fig.5

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